

Microsystems in Practice June 1-2 2004, Zweibrücken

Education Partnership and Sharing of Precious Resources in MST:

the Network **pro-mst**

Aus- und Weiterbildungsnetzwerk
für Prozesstechnologien in der
Mikrosystemtechnik



- **Andreas Schütze**
Saarland University, Saarbrücken
- **Antoni Picard**
University of Applied Sciences Kaiserslautern,
Campus Zweibrücken



Motivation I: FH Zweibrücken



Lithography
class 10

- ☺ Excellent technical infrastructure
(300 m² MST cleanroom for
complete process runs)
dedicated to education.

- ☹ Sustaining the cleanroom requires a
minimum size, i.e. a **critical mass**
of personnel and funding:

- **Too much for only education**

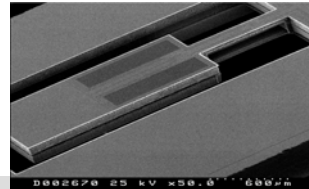
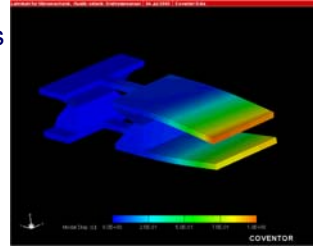
Generally financed by research, which
then often prevents proper education



Thin film technology
class 100

Motivation II: Saarland University

- Dept. of Mechatronics with research focus on MST
 - Measurement tech., esp. microsensors
 - Micromechanics, microactuators/-fluidics
 - Materials for MST
 - Medical microtechnology
- ☺ Excellent theoretical education
- ☺ International research projects
- ☹ **Limited technology** (only for specific process steps)
- ☹ **Limited practical experience** for students



Motivation III

- HTW Saarbrücken, FH Aachen
 - Similar to Saarland University
- Research institutes (FhG-IBMT, IMM Mainz)
 - Training of new technicians and research personnel
 - Avoiding costly errors with downtime of critical equipment
- Companies (HYDAC, thinXXS)
 - Training of personnel
 - Cooperation in development with new processes

! All need more students, technicians and researchers

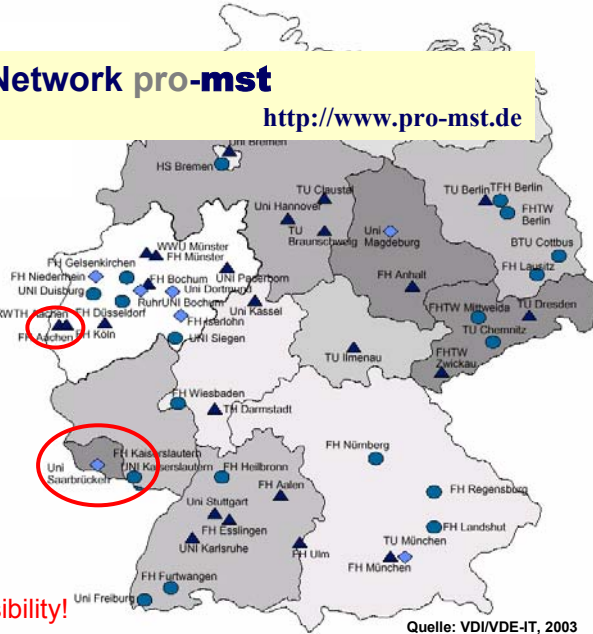
Partners:

- 4 Universities
- 2 R&D-institutes
- 2 Companies
- 4 Pilot-schools

From 3 federal states:

- Rheinland-Pfalz
- Saarland
- Nordrhein-Westfalen

Education is state responsibility!



Quelle: VDI/VDE-IT, 2003

- Cooperation in education and research
 - joint effort in developing courses and training materials
 - joint definition of research projects
- Cooperation in financing the clean room used by all
- Joint PR activities in schools to increase interest in MST and technical disciplines in general
- **Ultimately:** Strengthening the economic competitiveness of the region Westpfalz/Saarland (still depending on coal and steel)

Examples for cooperation with schools

- MST introductory courses for teachers
 - Introduction to MST technologies, components and applications
 - MST-examples and experiments for use in classes (physics, tech)
- MST workshops in the cleanroom
 - Photolithography
 - Microstructure characterization
- Support of school projects
 - Sensors for a wind tunnel
 - Go-kart with micro-sensors



Examples for cooperation in education

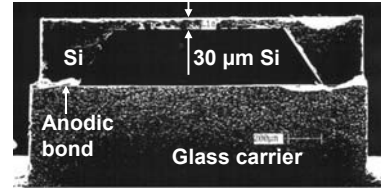
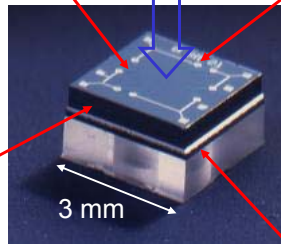
- Hands-on courses in the cleanroom in Zweibrücken for students from Saarland University
 - **Prerequisite:** courses in MST supplied by home university
 - **Preparation:** 3-day block course using the Virtual Cleanroom tools developed in the project ing-media (presented by A. Picard)
 - **Five day hands-on course** in Zweibrücken: complete process run for a simple pressure sensor (4 mask layers) from wafer preparation to sensor characterization
 - **Staffed from both** Zweibrücken and Saarland University

4 piezo-resistive strain gauges in Si-membrane (bridge configuration)

pressure

Al leads and bondpads ("sputtered thin film")

Si-chip with micromachined membrane (back-side etch)



Packaging: Si-chip bonded to glass carrier („Anodic bonding“)

n-type Wafer, 4", 400µm Gesamtdicke, beidseitig poliert, <100>-Orientierung				
Nr.	Prozess	SiO ₂ -Maske für Dotierschritt	Parameter	Schnittschema
Piezo-resistive Widerstände				
1	Thermisches SiO ₂ Feuchtoxidation	bedseitig Feuchtoxidation erzeugen einer Isolationschicht und Atzmaskegrundlage	Oxidationsstufe: 1000°C, 1h; +Heiß 90°C, Temperatur: 25min N ₂ , Cool-down CO ₂ neutral 12h; Abkühlung 25min, N ₂	
2	Haftvermittler Softbake	bedseitig Haftvermittler auftragen, für eine bessere Haftung des Fotolacks während des Ätprozesses	Haftvermittler (AR 300-80, Alresist) 1ml; Schleudern: 3000rpm, 1 min; Trocknen: 170°C/2min	
3	Belackern Softbake Belichten Entwickeln	Widerstandsmaske Halbmaste M1 auf Widerstandsmaske M2 abschieben, Proximity-Belichtung der Waferhälfte W1 mit M1-Maske horizontal drehen und Belichtung für VC wiederholen	Lack (AR-P-310010, Alresist) 1:1 2ml; Schleudern: 3000U/min/1min; Trocknen 87°C/2min; Belichten: Maske 1, Prox.-Abstand 20µm, 17sec; Entwickler (AR00026, Alresist), 1min 45sec; Spülen: DI-Wasser; Trocknen: 3000rpm, 30sec	
4	SiO ₂ -Ätzen	Widerstandsmaske HF-Ätzen, erzeugen einer Diffusionsmaske (Widerstandsstruktur) in der SiO ₂ -Oberfläche, anschließend Spülen/Trocknen	Ätzen: BHF-Ätzlösung 1mol HF, 2,8 mol H ₂ SO ₄ , Ätzrate 20nm/min, 20°C, 80min (zum SiO ₂); Spülen: DI-Wasser 30min; Trocknen: 3000rpm, 30sec	
Bor-Dotieren und BSG-Isolation				
5	Lack entfernen Spin-on-Dopant aufschleudern	bedseitig Strippen Lack und Haftvermittler entfernen, spülen, trocknen, Widerstandsmaske Spin-on Dopant auf die strukturierte SiO ₂ -Seite auftragen	Strippen ca. 30 sec mit Aceton spülen bis Oberfläche lackfrei ist; Spülen: DI-Wasser; Trocknen: 3000rpm, 30sec; bei P&A Dopant 1,5ml aufschleudern 3000rpm, 20sec; Trocknen: 100°C/60sec	
6	Diffusion	P-dotieren: Widerstandsdrähte (an den paraffinierten SiO ₂ -Stellen) erzeugen; Diffusionsstufe wird vertempert, Wafer werden abführen und bei Diffusionsprozess gestochen.	Diffusionsmaske vertempertieren 87°C, 25min N ₂ ; Diffundieren: 1000°C, 40min N ₂ , 1000ccm O ₂ , 15min; Abkühlen: 45min, 25min N ₂ , auf ca. 85°C	
7	Verglasen Abkühlung	Verglasen: Spin-on-Dopant wandelt sich unter Wasserdampfzugabe zu Borisilatgas.	Diffusionsmaske verglasen 1000°C, 40min N ₂ , 200ccm O ₂ ; Dübelen: 15min; Abkühlen: 45min, 25min N ₂ , auf ca. 85°C	
8	Al-Ätzen Lack entfernen Spülen Formieren	Widerstandsmaske Aluminium stören mit H ₂ PO ₄ und HNO ₃ Strippen	Ätzen: Ätzlösung 1mol HF, 2,8 mol H ₂ SO ₄ ; 20°C, 80min (zum SiO ₂); Spülen: DI-Wasser 30min; Trocknen: 3000rpm, 30sec	
9	Al-Ätzen Lack entfernen Spülen Formieren	Widerstandsmaske Aluminium stören mit H ₂ PO ₄ und HNO ₃ Strippen	Ätzen: Ätzlösung 1mol HF, 2,8 mol H ₂ SO ₄ ; 20°C, 80min (zum SiO ₂); Spülen: DI-Wasser 30min; Trocknen: 3000rpm, 30sec	
10	Al-Ätzen Lack entfernen Spülen Formieren	Widerstandsmaske Aluminium stören mit H ₂ PO ₄ und HNO ₃ Strippen	Ätzen: Ätzlösung 1mol HF, 2,8 mol H ₂ SO ₄ ; 20°C, 80min (zum SiO ₂); Spülen: DI-Wasser 30min; Trocknen: 3000rpm, 30sec	

"Simple" pressure sensor: more than 100 process steps



The Future I: Cooperation with other Universities

- Courses offered to Higher Education Institutions
 - Nationally and internationally
 - Course program developed cooperatively adapted to education requirements of home university
 - Cost participation based on clean room and personnel costs
necessary: 15 k€ for 5-day course for 12 participants
- R&D project support to realize own designs
 - Multi-project wafers with standardized process for education
 - Lower cost than foundry process for use in project groups
- Extension of cooperation to other technology fields?



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The Future II: Commercial hands-on courses

- Course program making use of
 - Technical infrastructure (i.e. cleanroom, test equipment etc.)
 - Know-how available through the partners**Aim:** supplementing University funding for the cleanroom
- Advantage for companies and R&D institutes
 - Training of new staff without interrupting production
 - Preventing operating errors resulting in equipment downtime
- Standard courses
- User defined courses for specific requirements, i.e. regular training of new staff for companies



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Cleanroom techn. and correct cleanroom behavior

- 2-day course
 - **Lectures**
 - Cleanroom technology, equipment and clothing
 - Cleanroom behavior
 - Measurement technology for cleanroom characterization
 - **Hands-on modules**
 - Correct clothing and behavior in the cleanroom
 - Use of cleanroom equipment
- Maximum 12 participants
- Cost: approx. 700 € per participant

MST technologies, components and applications

- 3-day course with hands-on modules
 - **Lectures** giving an introduction
 - Microtechnologies (lithography, thin-film technology) and equipment, characterisation and testing
 - Microcomponents, -sensors, -actuators and systems
 - MST applications
 - **Hands-on modules**
 - Lithography
 - Thin-film deposition
 - Sensor characterization
- Max. 9 participants, approx. 1200 € per participant

- 👉 New approach for sharing of precious resources:
Partnership in education and research
- 👉 Example for public private partnership
- 👉 Applicable not only to MST
- 👉 Solutions for financing across state borders required
- ✂️ **Please contact us for course requests/requirements**



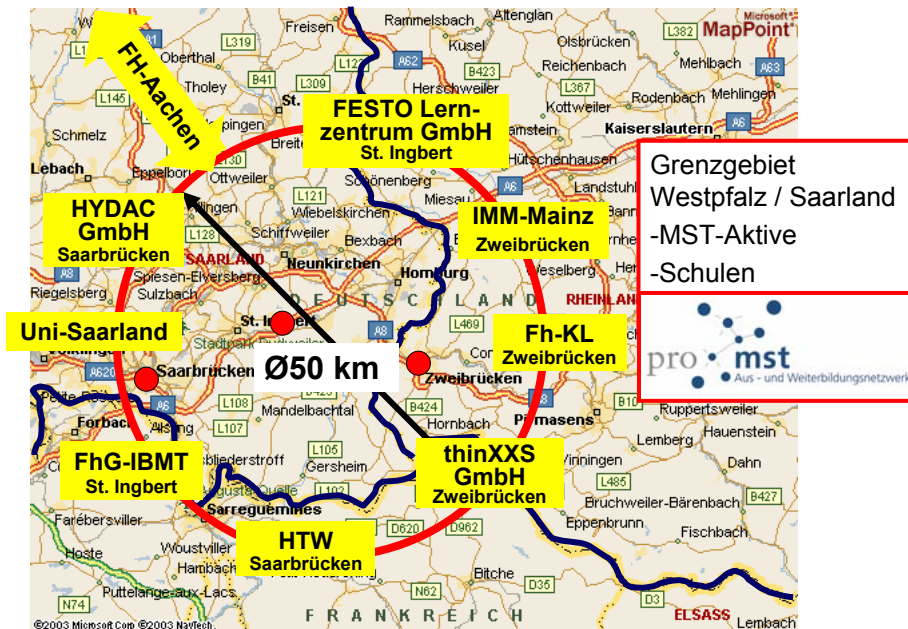
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